

STACKED IC

ABSTRACT OF THE DISCLOSURE

A stacked IC includes a first IC package unit, a second IC package unit and an interface layer. The first IC package unit includes an IC chip, an encapsulant resin and a plurality of lead wires. The IC chip is encapsulated by the encapsulant resin. Each of the lead wires includes a first end connected to the IC chip and encapsulated by the encapsulant resin and a second end extending outside the encapsulant resin. The interface layer has a first side connected to soldering portions of the lead wires of the first IC package unit via a plurality of solder balls and a second side connected to the second IC package unit.